

MDP4N60/MDF4N60

N-Channel MOSFET 600V, 4.6A, 2.0Ω

General Description

These N-channel MOSFET are produced using advanced MagnaChip's MOSFET Technology, which provides low on-state resistance, high switching performance and excellent quality.

These devices are suitable device for SMPS, high Speed switching and general purpose applications.

Features

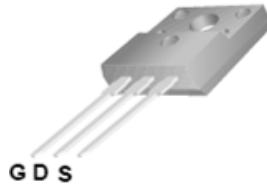
- $V_{DS} = 600V$
- $I_D = 4.6A$ @ $V_{GS} = 10V$
- $R_{DS(ON)} \leq 2.0\Omega$ @ $V_{GS} = 10V$

Applications

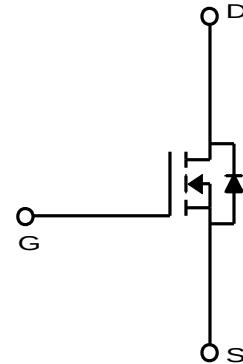
- Power Supply
- PFC
- High Current, High Speed Switching



TO-220
MDP Series



TO-220F
MDF Series



Absolute Maximum Ratings ($T_a = 25^\circ C$)

Characteristics		Symbol	MDP4N60	MDF4N60	Unit
Drain-Source Voltage		V_{DSS}	600		V
Gate-Source Voltage		V_{GSS}	± 30		V
Continuous Drain Current	$T_C = 25^\circ C$	I_D	4.6	4.6*	A
	$T_C = 100^\circ C$		2.9	2.9*	A
Pulsed Drain Current ⁽¹⁾		I_{DM}	18.4	18.4*	A
Power Dissipation	$T_C = 25^\circ C$	P_D	92.5	34.7	W
	Derate above $25^\circ C$		0.74	0.28	W/ $^\circ C$
Repetitive Avalanche Energy ⁽¹⁾		E_{AR}	9.25		mJ
Peak Diode Recovery dv/dt ⁽³⁾		dv/dt	4.5		V/ns
Single Pulse Avalanche Energy ⁽⁴⁾		E_{AS}	170		mJ
Junction and Storage Temperature Range		T_J, T_{stg}	$-55 \sim 150$		$^\circ C$

* I_D limited by maximum junction temperature

Thermal Characteristics

Characteristics	Symbol	MDP4N60	MDF4N60	Unit
Thermal Resistance, Junction-to-Ambient ⁽¹⁾	$R_{\theta JA}$	62.5	62.5	$^\circ C/W$
Thermal Resistance, Junction-to-Case ⁽¹⁾	$R_{\theta JC}$	1.35	3.6	

Ordering Information

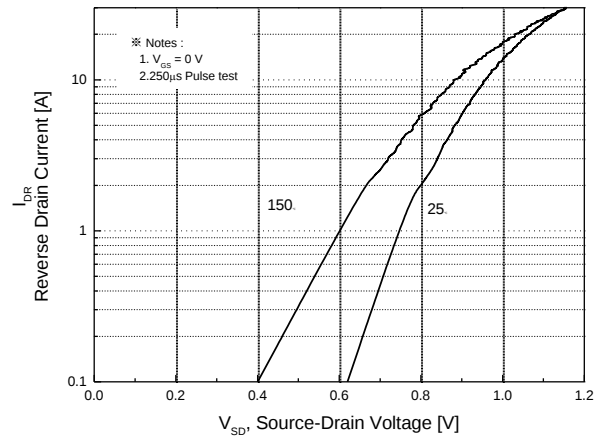
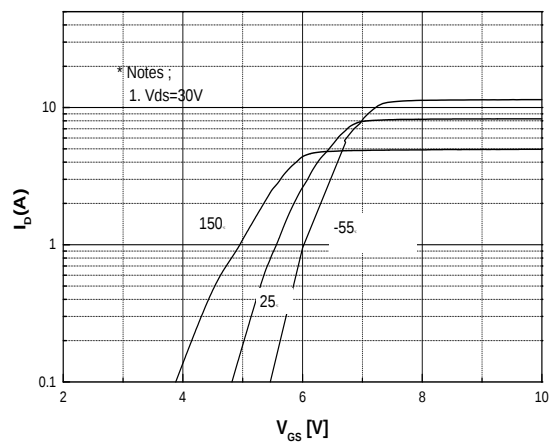
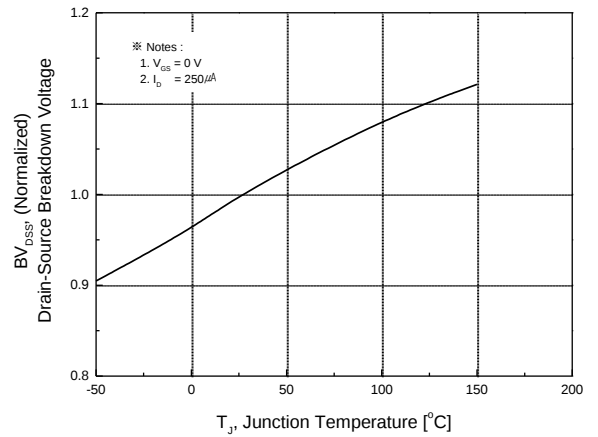
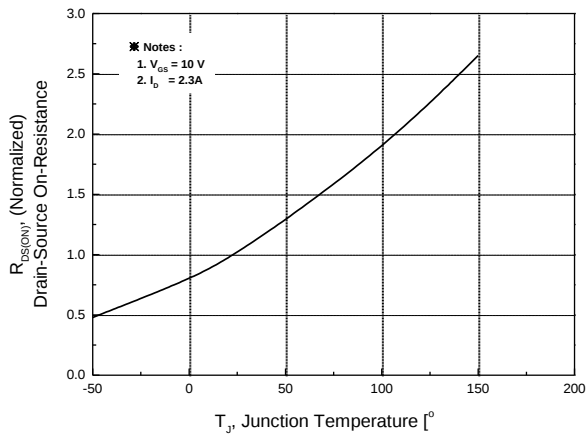
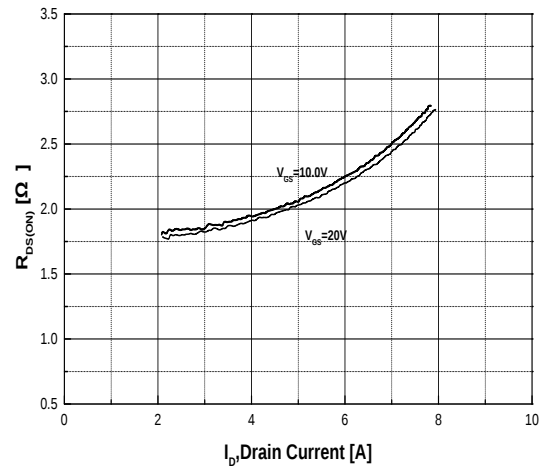
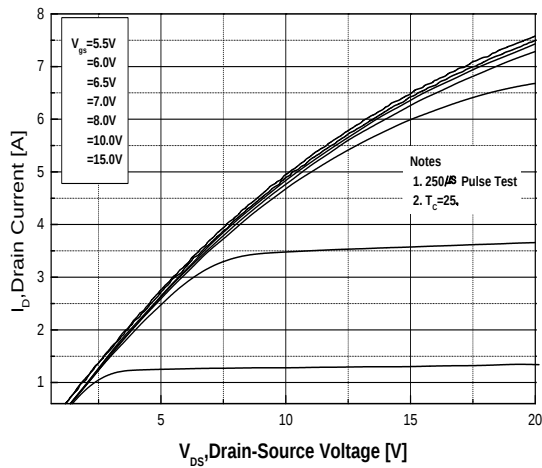
Part Number	Temp. Range	Package	Packing	RoHS Status
MDP4N60TH	-55~150°C	TO-220	Tube	Halogen Free
MDF4N60TH	-55~150°C	TO-220F	Tube	Halogen Free
MDP4N60TP	-55~150°C	TO-220	Tube	Pb Free
MDF4N60TP	-55~150°C	TO-220F	Tube	Pb Free

Electrical Characteristics (Ta =25°C)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D = 250\mu A, V_{GS} = 0V$	600	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	3.0	-	5.0	
Drain Cut-Off Current	I_{DSS}	$V_{DS} = 600V, V_{GS} = 0V$	-	-	1	μA
Gate Leakage Current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	100	nA
Drain-Source ON Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 2.3A$		1.7	2.0	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 30V, I_D = 2.3A$	-	4	-	S
Dynamic Characteristics						
Total Gate Charge	Q_g	$V_{DS} = 480V, I_D = 4.6A, V_{GS} = 10V^{(3)}$	-	12.1	-	nC
Gate-Source Charge	Q_{gs}		-	3.5	-	
Gate-Drain Charge	Q_{gd}		-	4.4	-	
Input Capacitance	C_{iss}	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$	-	506	660	pF
Reverse Transfer Capacitance	C_{rss}		-	2.3	3	
Output Capacitance	C_{oss}		-	58	75	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DS} = 300V, I_D = 4.6A, R_G = 25\Omega^{(3)}$	-	12	-	ns
Rise Time	t_r		-	20	-	
Turn-Off Delay Time	$t_{d(off)}$		-	27	-	
Fall Time	t_f		-	20	-	
Drain-Source Body Diode Characteristics						
Maximum Continuous Drain to Source Diode Forward Current	I_S		-	4.6	-	A
Source-Drain Diode Forward Voltage	V_{SD}	$I_S = 4.6A, V_{GS} = 0V$	-	-	1.4	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 4.6A, di/dt = 100A/\mu s^{(3)}$	-	243	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	1.5	-	μC

Note :

1. Pulse width is based on $R_{\theta JC}$ & $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C.
2. Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ C$.
3. $I_{SD} \leq 4.6A$, $di/dt \leq 200A/\mu s$, $V_{DD}=50V$, $R_G=25\Omega$, Starting $T_J=25^\circ C$
4. $L=14.8mH$, $I_{AS}=4.6A$, $V_{DD}=50V$, $R_G=25\Omega$, Starting $T_J=25^\circ C$,



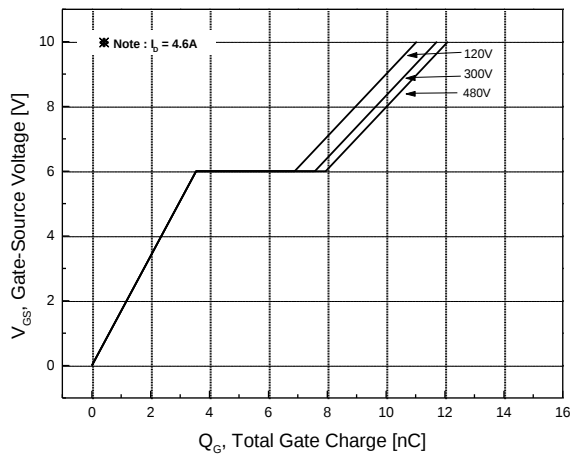


Fig.7 Gate Charge Characteristics

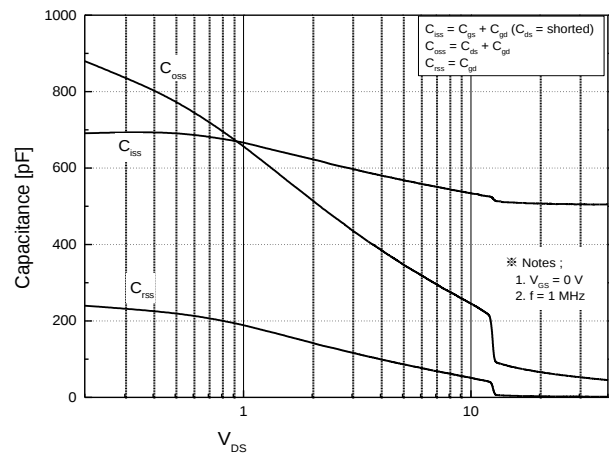


Fig.8 Capacitance Characteristics

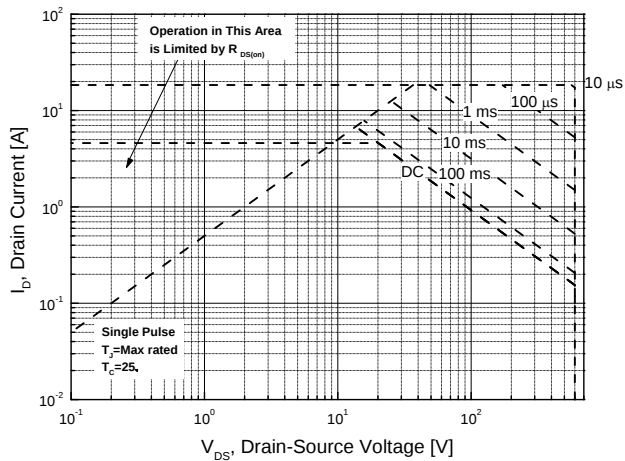


Fig.9 Maximum Safe Operating Area
MDP4N60 (TO-220)

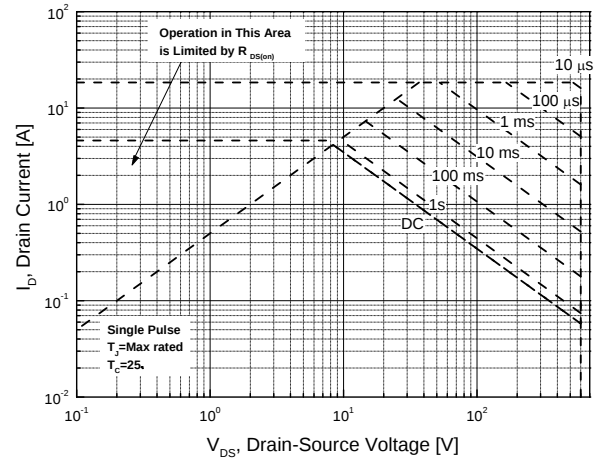


Fig.10 Maximum Safe Operating Area
MDF4N60 (TO-220F)

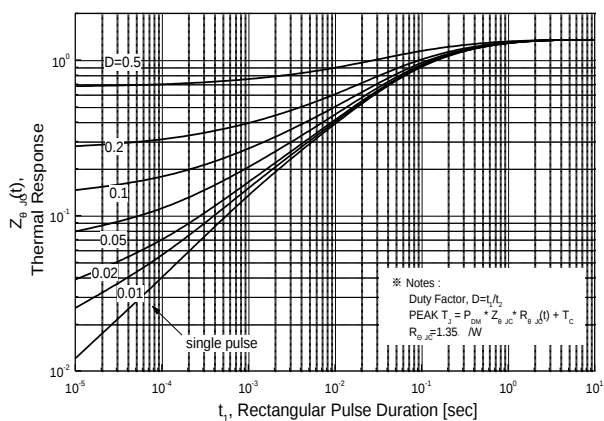


Fig.11 Transient Thermal Response Curve
MDP4N60 (TO-220)

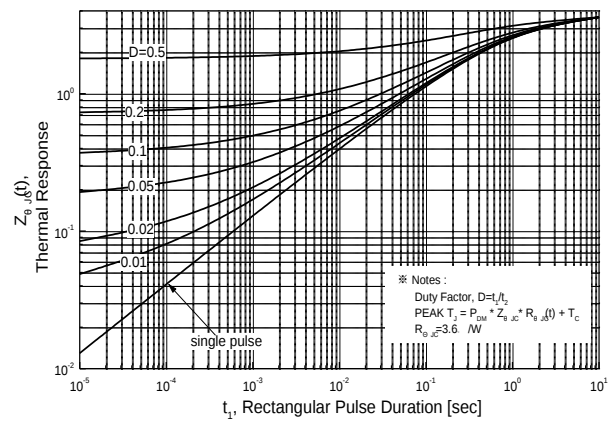


Fig.12 Transient Thermal Response Curve
MDF4N60 (TO-220F)

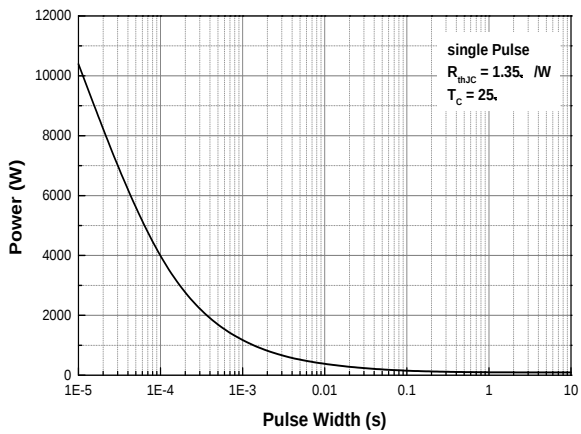


Fig.13 Single Pulse Maximum Power Dissipation MDP4N60 (TO-220)

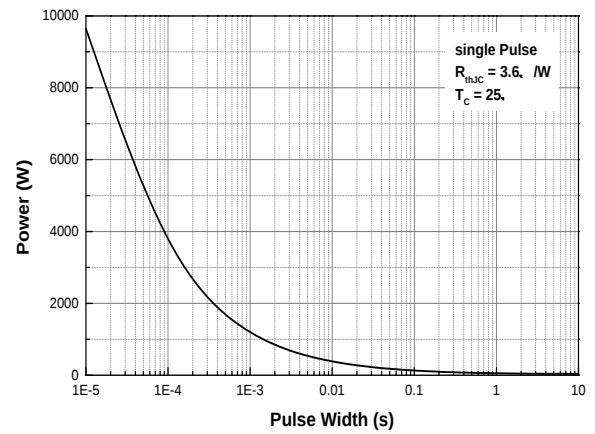


Fig.14 Single Pulse Maximum Power Dissipation MDF4N60 (TO-220F)

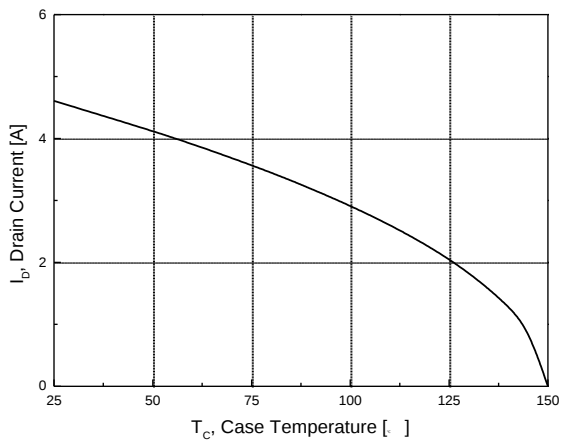
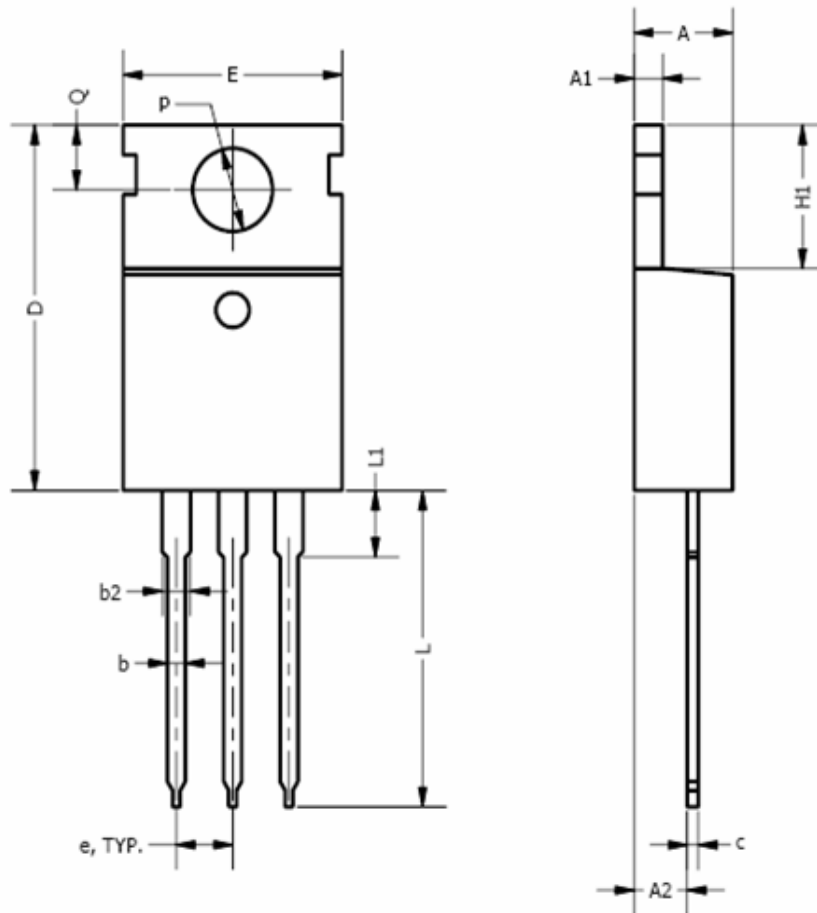


Fig.15 Maximum Drain Current vs. Case Temperature

Physical Dimensions

3 Leads, TO-220

Dimensions are in millimeters unless otherwise specified

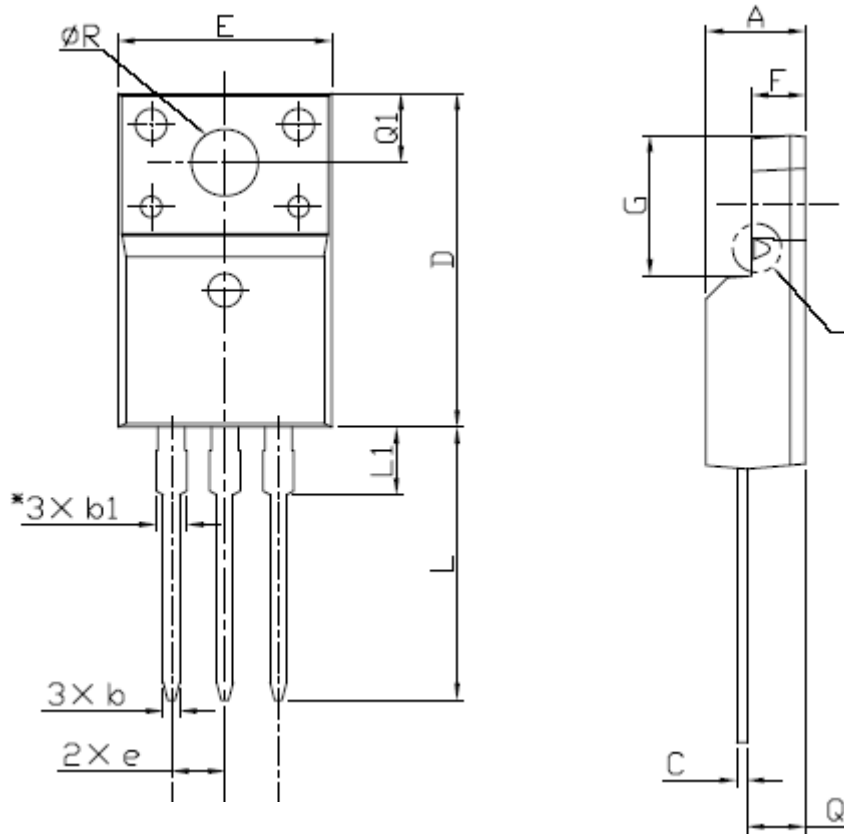


Symbol	Min	Nom	Max
A	3.56		4.83
A1	0.50		1.40
A2	2.03		2.92
b	0.38	0.69	1.02
b2	1.14	1.45	1.78
c	0.36		0.61
D	14.22		16.51
e	2.54 TYP		
E	9.65		10.67
H1	5.84		6.86
L	12.70		14.73
L1			6.35
ϕP	3.53		4.09
Q	2.54		3.43

Physical Dimensions

3 Leads, TO-220F

Dimensions are in millimeters unless otherwise specified



Symbol	Min	Nom	Max
A	4.50		4.93
b	0.63		0.91
b1	1.15		1.47
C	0.33		0.63
D	15.47		16.13
E	9.60		10.71
e		2.54	
F	2.34		2.84
G	6.48		6.90
L	12.24		13.72
L1	2.79		3.67
Q	2.52		2.96
Q1	3.10		3.50
ØR	3.00		3.55

